



RELIABILITY REPORT
FOR
MAX4166EUA+
PLASTIC ENCAPSULATED DEVICES

February 29, 2012

MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX4166EUA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX4165-MAX4169 family of operational amplifiers combines excellent DC accuracy with high output current drive, single-supply operation, and rail-to-rail inputs and outputs. These devices operate from a single +2.7V to +6.5V supply, or from dual $\pm 1.35\text{V}$ to $\pm 3.25\text{V}$ supplies. They typically draw 1.2mA supply current, and are guaranteed to deliver 80mA output current. The MAX4166/MAX4168 have a shutdown mode that reduces supply current to 38 μA per amplifier and places the outputs into a high-impedance state. The MAX4165-MAX4169's precision performance combined with high output current, wide input/output dynamic range, single-supply operation, and low power consumption makes them ideal for portable audio applications and other low-voltage, battery-powered systems. The MAX4165 is available in the space-saving 5-pin SOT23 package and the MAX4166 is available in a tiny 2mm x 2mm x 0.8mm μDFN package.

II. Manufacturing Information

A. Description/Function:	High-Output-Drive, Precision, Low-Power, Single-Supply, Rail-to-Rail I/O Op Amps with Shutdown
B. Process:	CB20
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Thailand, Malaysia
F. Date of Initial Production:	April 26, 1997

III. Packaging Information

A. Package Type:	3x3 mm 8L UMAX
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-3001-0016 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	221°C/W
K. Single Layer Theta Jc:	42°C/W
L. Multi Layer Theta Ja:	206.3°C/W
M. Multi Layer Theta Jc:	42°C/W

IV. Die Information

A. Dimensions:	57 X 38 mils
B. Passivation:	Si ₃ N ₄ (Silicon nitride)
C. Interconnect:	Au
D. Backside Metallization:	None
E. Minimum Metal Width:	2 microns (as drawn)
F. Minimum Metal Spacing:	2 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{1000 \times 4340 \times 402 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 0.5 \times 10^{-9}$$

$$\lambda = 0.5 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the CB20 Process results in a FIT Rate of 0.14 @ 25C and 2.48 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot BB6ABX003A D/C 9711)

The OP16 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX4166EUA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 1000 hrs.	DC Parameters & functionality	80	0	NB6ACA090H, D/C 0625
			45	0	NB6ACA080Q, D/C 0540
			45	0	NB6ACA076Q, D/C 0527
			77	0	NB6ACA086D, D/C 0548
			79	0	NB6ACA102A, D/C 0731
			76	0	NB6ACA068E, D/C 0450

Note 1: Life Test Data may represent plastic DIP qualification lots.